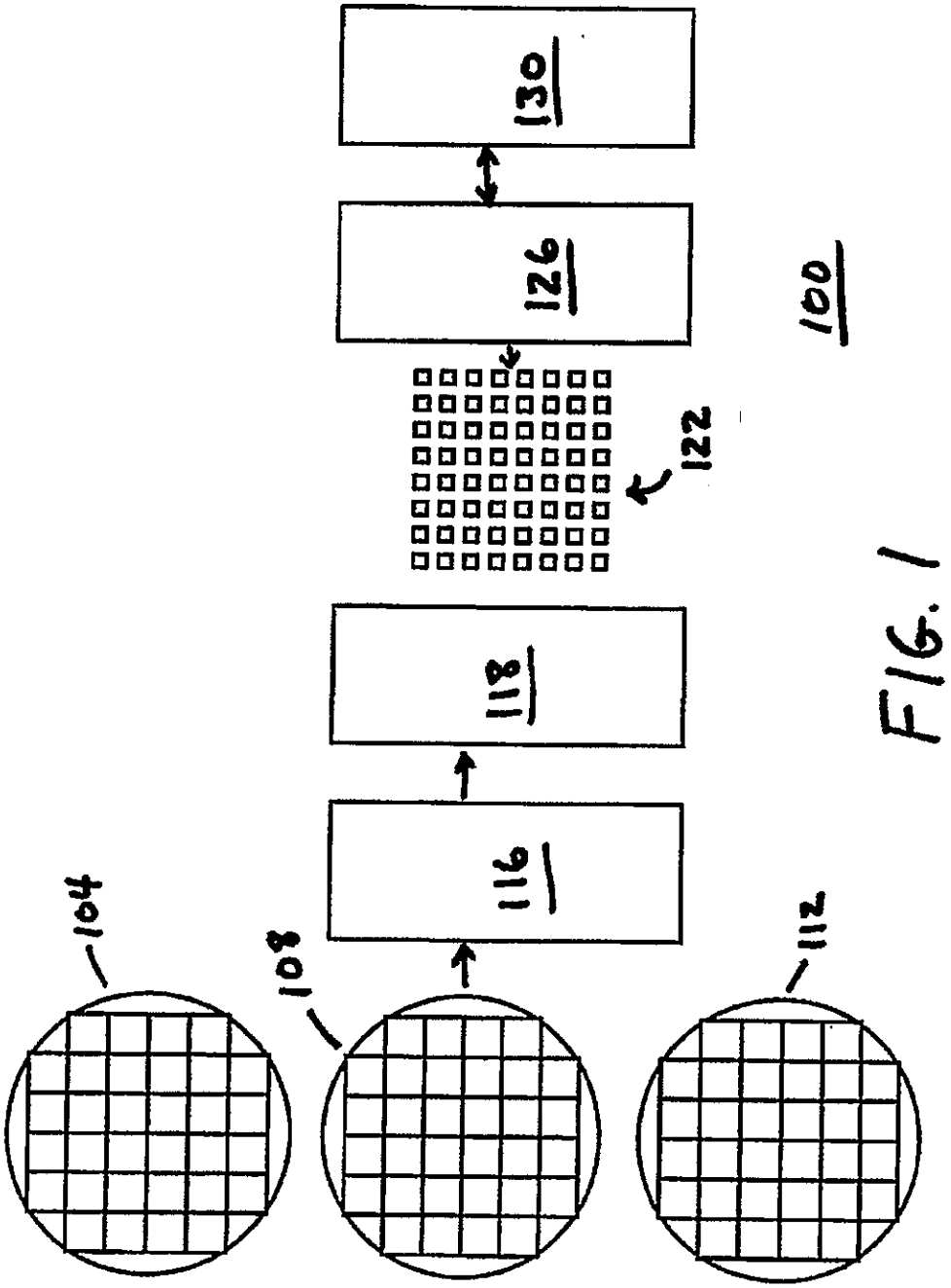

FIG. 1

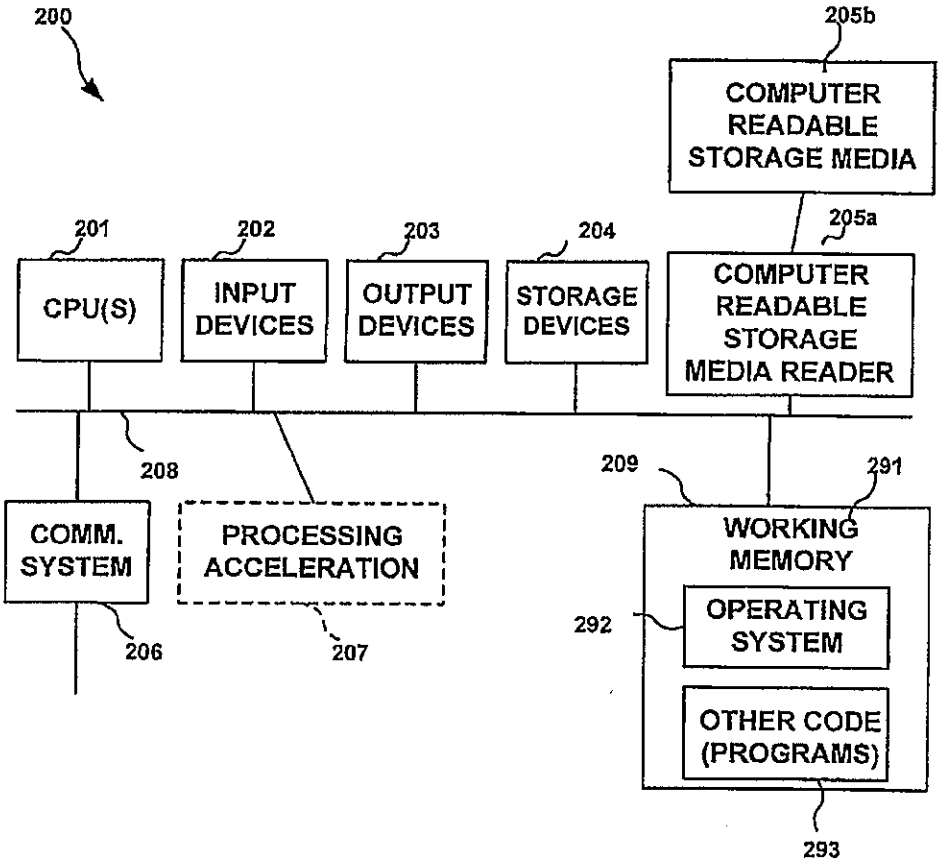
200
205b
COMPUTER READABLE STORAGE MEDIA
205a
201
202
203
204
CPU(S)
INPUT DEVICES
OUTPUT DEVICES
STORAGE DEVICES
COMPUTER READABLE STORAGE MEDIA READER
208
209
291
COMM. SYSTEM
PROCESSING ACCELERATION
WORKING MEMORY
292
OPERATING SYSTEM
OTHER CODE (PROGRAMS)
206
207
293

FIG. 2

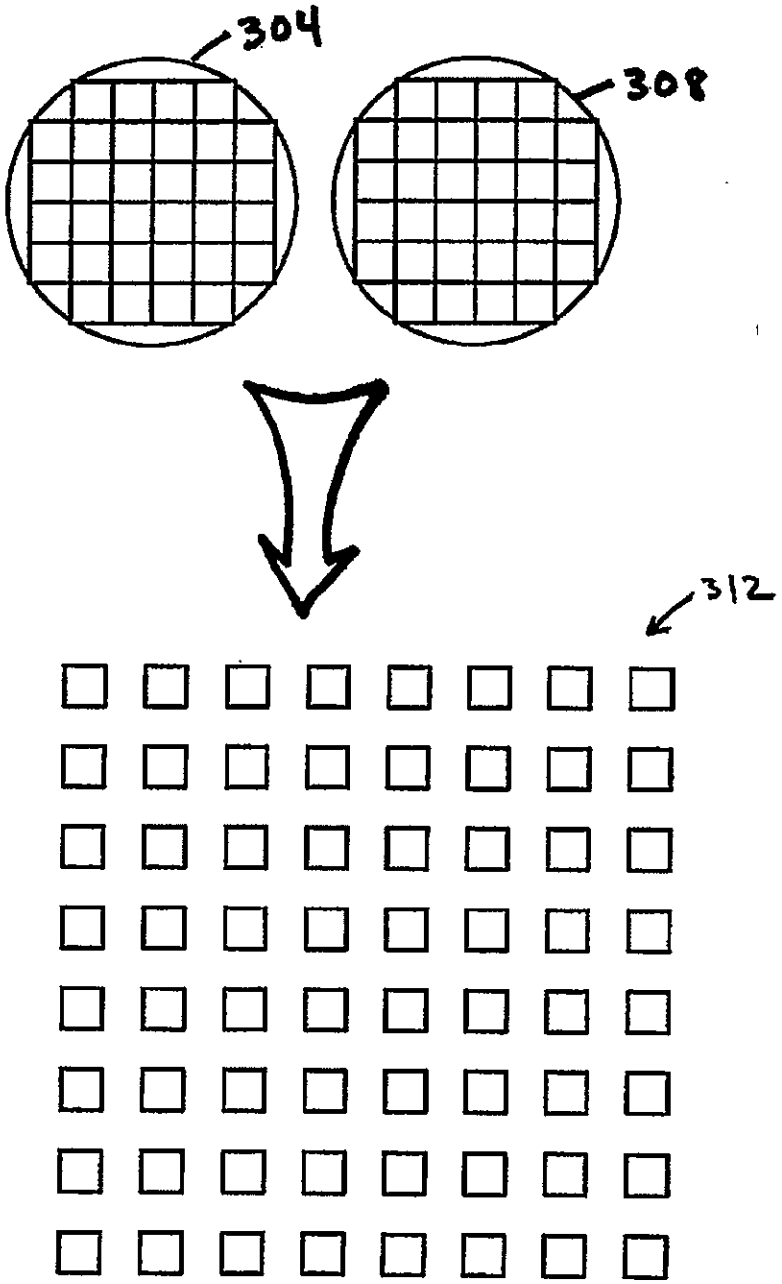

FIG. 3

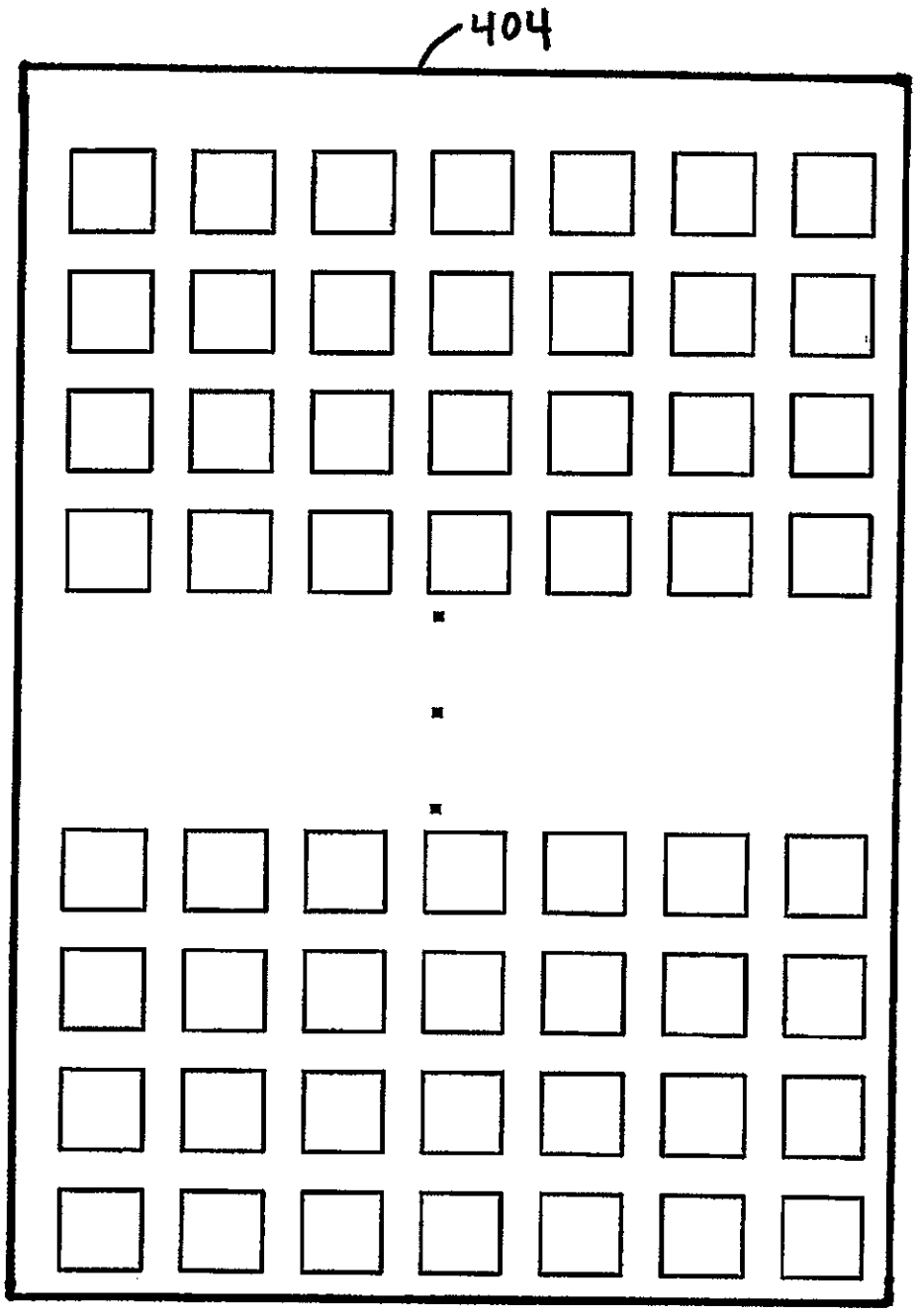

FIG. 4

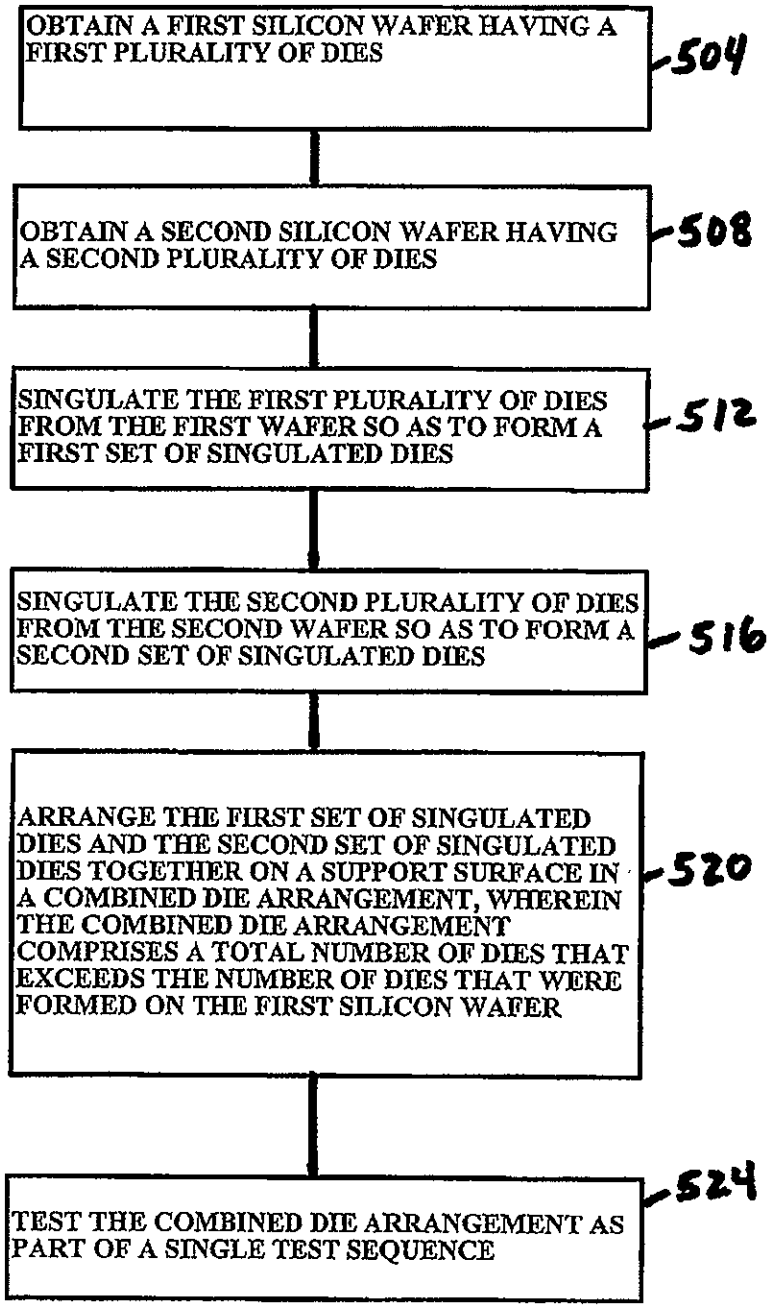
OBTAIN A FIRST SILICON WAFER HAVING A FIRST PLURALITY OF DIES
504
OBTAIN A SECOND SILICON WAFER HAVING A SECOND PLURALITY OF DIES
508
SINGULATE THE FIRST PLURALITY OF DIES FROM THE FIRST WAFER SO AS TO FORM A FIRST SET OF SINGULATED DIES
512
SINGULATE THE SECOND PLURALITY OF DIES FROM THE SECOND WAFER SO AS TO FORM A SECOND SET OF SINGULATED DIES
516
ARRANGE THE FIRST SET OF SINGULATED DIES AND THE SECOND SET OF SINGULATED DIES TOGETHER ON A SUPPORT SURFACE IN A COMBINED DIE ARRANGEMENT, WHEREIN THE COMBINED DIE ARRANGEMENT COMPRISES A TOTAL NUMBER OF DIES THAT EXCEEDS THE NUMBER OF DIES THAT WERE FORMED ON THE FIRST SILICON WAFER
520
TEST THE COMBINED DIE ARRANGEMENT AS PART OF A SINGLE TEST SEQUENCE
524

FIG. 5 500

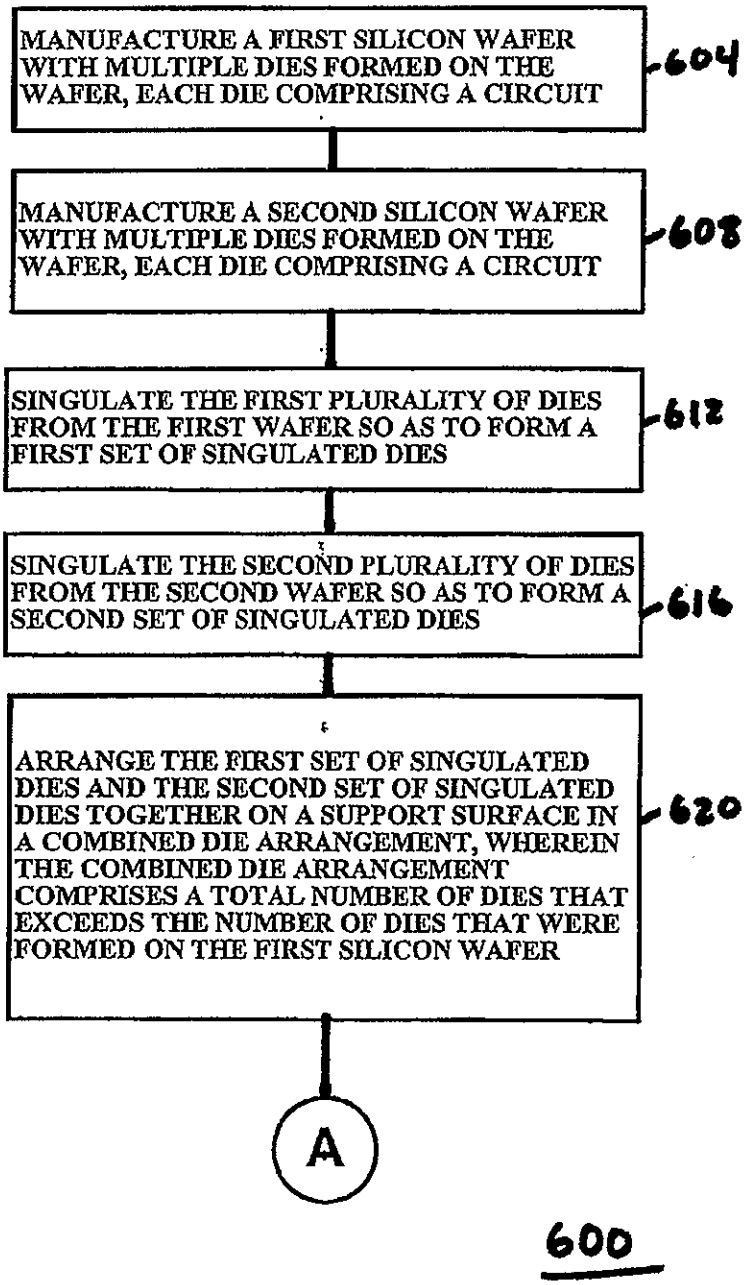
MANUFACTURE A FIRST SILICON WAFER WITH MULTIPLE DIES FORMED ON THE WAFER, EACH DIE COMPRISING A CIRCUIT
604
MANUFACTURE A SECOND SILICON WAFER WITH MULTIPLE DIES FORMED ON THE WAFER, EACH DIE COMPRISING A CIRCUIT
608
SINGULATE THE FIRST PLURALITY OF DIES FROM THE FIRST WAFER SO AS TO FORM A FIRST SET OF SINGULATED DIES
612
SINGULATE THE SECOND PLURALITY OF DIES FROM THE SECOND WAFER SO AS TO FORM A SECOND SET OF SINGULATED DIES
616
ARRANGE THE FIRST SET OF SINGULATED DIES AND THE SECOND SET OF SINGULATED DIES TOGETHER ON A SUPPORT SURFACE IN A COMBINED DIE ARRANGEMENT, WHEREIN THE COMBINED DIE ARRANGEMENT COMPRISES A TOTAL NUMBER OF DIES THAT EXCEEDS THE NUMBER OF DIES THAT WERE FORMED ON THE FIRST SILICON WAFER
620
A
600

FIG. 6A

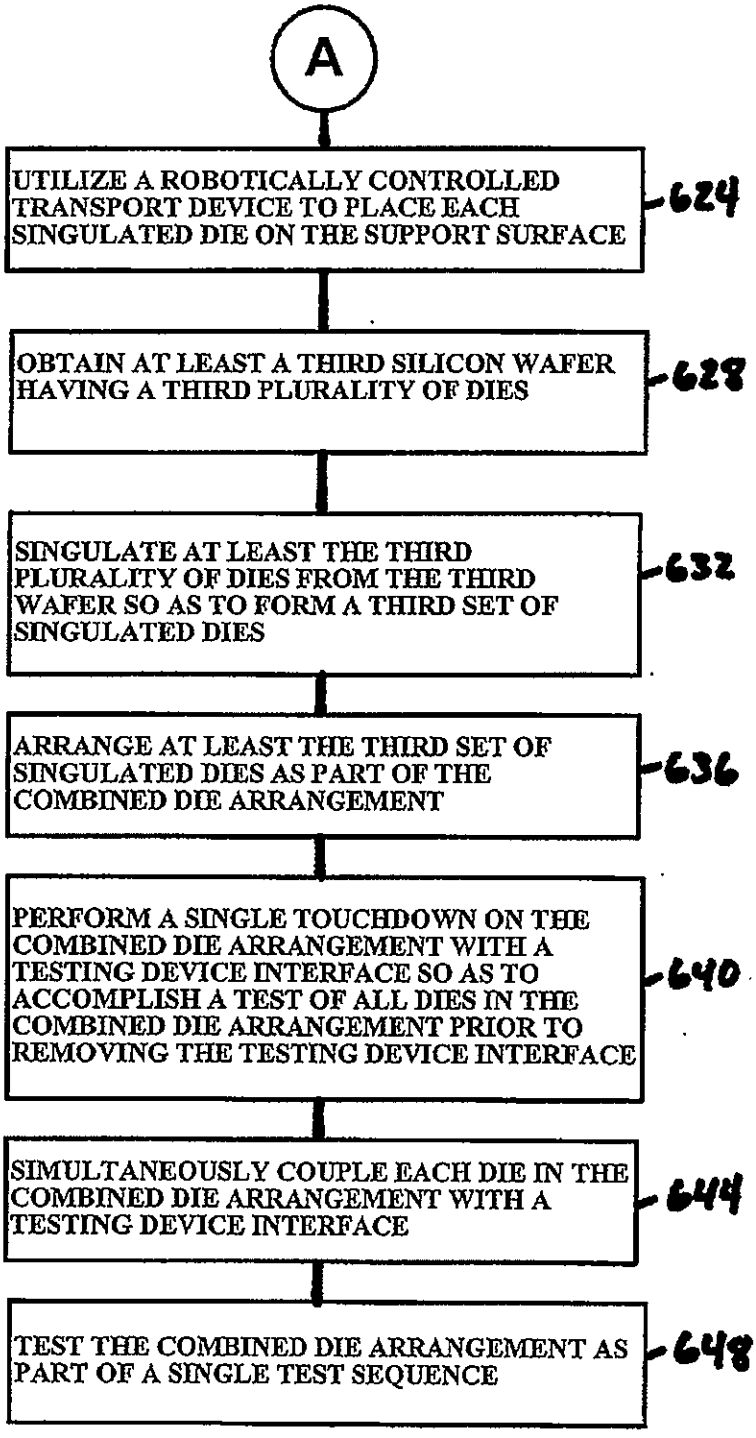
A
UTILIZE A ROBOTICALLY CONTROLLED TRANSPORT DEVICE TO PLACE EACH SINGULATED DIE ON THE SUPPORT SURFACE
624
OBTAIN AT LEAST A THIRD SILICON WAFER HAVING A THIRD PLURALITY OF DIES
628
SINGULATE AT LEAST THE THIRD PLURALITY OF DIES FROM THE THIRD WAFER SO AS TO FORM A THIRD SET OF SINGULATED DIES
632
ARRANGE AT LEAST THE THIRD SET OF SINGULATED DIES AS PART OF THE COMBINED DIE ARRANGEMENT
636
PERFORM A SINGLE TOUCHDOWN ON THE COMBINED DIE ARRANGEMENT WITH A TESTING DEVICE INTERFACE SO AS TO ACCOMPLISH A TEST OF ALL DIES IN THE COMBINED DIE ARRANGEMENT PRIOR TO REMOVING THE TESTING DEVICE INTERFACE
640
SIMULTANEOUSLY COUPLE EACH DIE IN THE COMBINED DIE ARRANGEMENT WITH A TESTING DEVICE INTERFACE
644
TEST THE COMBINED DIE ARRANGEMENT AS PART OF A SINGLE TEST SEQUENCE
648

FIG. 6B